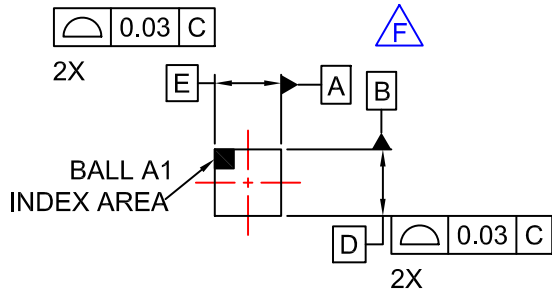
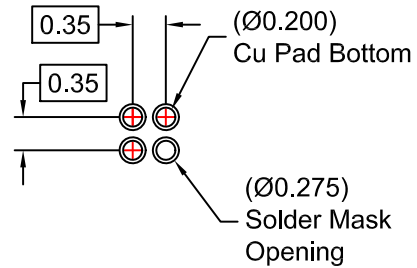


WLCSP4 0.65x0.65x0.298
CASE 567QC
ISSUE O

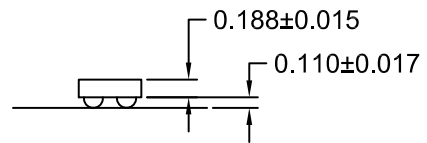
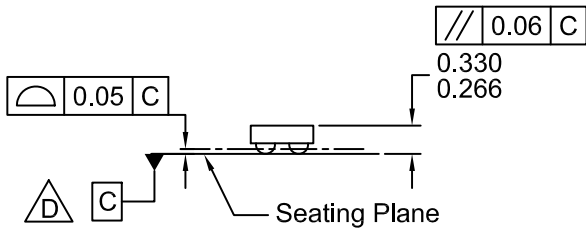
DATE 31 OCT 2016



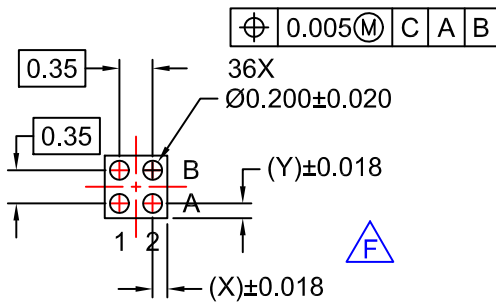
TOP VIEW



RECOMMENDED LAND PATTERN
(NSMD TYPE)



SIDE VIEWS



BOTTOM VIEW

NOTES

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCE PER ASME Y14.5M, 2009.
- D. DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
- E. PACKAGE NOMINAL HEIGHT IS 298 ± 32 MICRONS (266-330 MICRONS).
- F. FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.

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DESCRIPTION:	WLCSP4 0.65x0.65x0.298	PAGE 1 OF 1

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